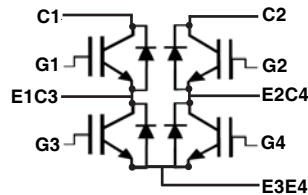


# High Voltage, High Gain BIMOSFET™ Monolithic Bipolar MOS Transistor

## MMIX4B22N300



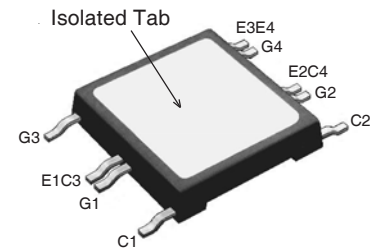
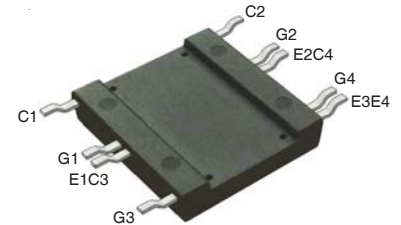
$$V_{CES} = 3000V$$

$$I_{C90} = 22A$$

$$V_{CE(sat)} \leq 2.7V$$

(Electrically Isolated Tab)

Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ C$ to $150^\circ C$	3000	V
$V_{CGR}$	$T_J = 25^\circ C$ to $150^\circ C$ , $R_{GE} = 1M\Omega$	3000	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ C$	38	A
$I_{C90}$	$T_C = 90^\circ C$	22	A
$I_{CM}$	$T_C = 25^\circ C$ , 1ms	165	A
<b>SSOA</b> <b>(RBSOA)</b>	$V_{GE} = 15V$ , $T_{VJ} = 125^\circ C$ , $R_G = 15\Omega$ Clamped Inductive Load	$I_{CM} = 180$ $V_{CES} \leq 1500$	A V
$T_{SC}$ <b>(SCSOA)</b>	$V_{GE} = 15V$ , $T_J = 125^\circ C$ , $R_G = 52\Omega$ , $V_{CE} = 1500V$ , Non-Repetitive	10	$\mu s$
$P_C$	$T_C = 25^\circ C$	150	W
$T_J$		-55 ... +150	$^\circ C$
$T_{JM}$		150	$^\circ C$
$T_{stg}$		-55 ... +150	$^\circ C$
$T_L$	Maximum Lead Temperature for Soldering	300	$^\circ C$
$T_{SOLD}$	Plastic Body for 10s	260	$^\circ C$
$F_C$	Mounting Force	50..200 / 11..45	N/lb
$V_{ISOL}$	50/60Hz, 1 minute	4000	V~
<b>Weight</b>		8	g



G = Gate                      E = Emitter  
C = Collector

### Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 4000V~ Electrical Isolation
- High Blocking Voltage
- High Peak Current Capability
- Low Saturation Voltage

### Advantages

- Low Gate Drive Requirement
- High Power Density

### Applications

- Switch-Mode and Resonant-Mode Power Supplies
- Capacitor Discharge Circuits

Symbol	Test Conditions ( $T_J = 25^\circ C$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{CES}$	$I_C = 250\mu A$ , $V_{GE} = 0V$	3000		V
$V_{GE(th)}$	$I_C = 250\mu A$ , $V_{CE} = V_{GE}$	3.0		5.0 V
$I_{CES}$	$V_{CE} = V_{CES}$ , $V_{GE} = 0V$ Note 2, $T_J = 125^\circ C$			35 $\mu A$ 1.5 mA
$I_{GES}$	$V_{CE} = 0V$ , $V_{GE} = \pm 20V$			$\pm 100$ nA
$V_{CE(sat)}$	$I_C = 22A$ , $V_{GE} = 15V$ , Note 1 $T_J = 125^\circ C$		2.2 2.7	V V

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$I_C = 22\text{A}, V_{CE} = 10\text{V}$ , Note 1	13	22	S
$C_{ies}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		2200	pF
$C_{oes}$			85	pF
$C_{res}$			30	pF
$Q_{g(on)}$	$I_C = 22\text{A}, V_{GE} = 15\text{V}, V_{CE} = 1500\text{V}$		110	nC
$Q_{ge}$			13	nC
$Q_{gc}$			45	nC
$t_{d(on)}$	<b>Resistive Switching Times, <math>T_J = 25^\circ\text{C}</math></b> $I_C = 22\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 960\text{V}, R_G = 15\Omega$		46	ns
$t_r$			360	ns
$t_{d(off)}$			205	ns
$t_f$			1820	ns
$t_{d(on)}$	<b>Resistive Switching Times, <math>T_J = 125^\circ\text{C}</math></b> $I_C = 22\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 960\text{V}, R_G = 15\Omega$		43	ns
$t_r$			700	ns
$t_{d(off)}$			220	ns
$t_f$			1650	ns
$R_{thJC}$			0.83	$^\circ\text{C/W}$
$R_{thCS}$		0.05		$^\circ\text{C/W}$
$R_{thJA}$		30		$^\circ\text{C/W}$

**Reverse Diode**

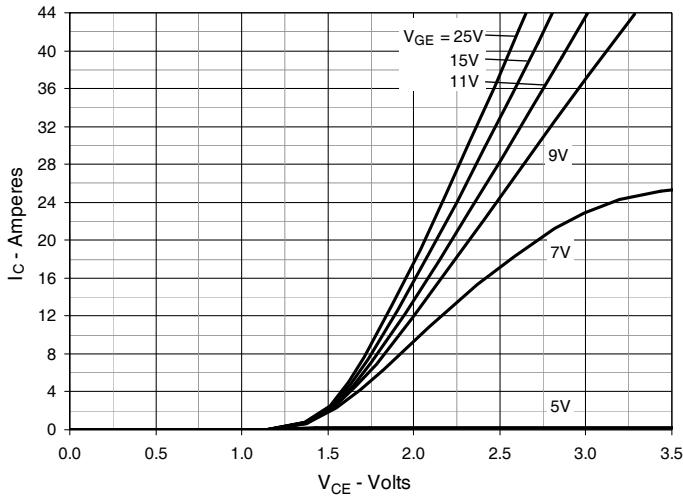
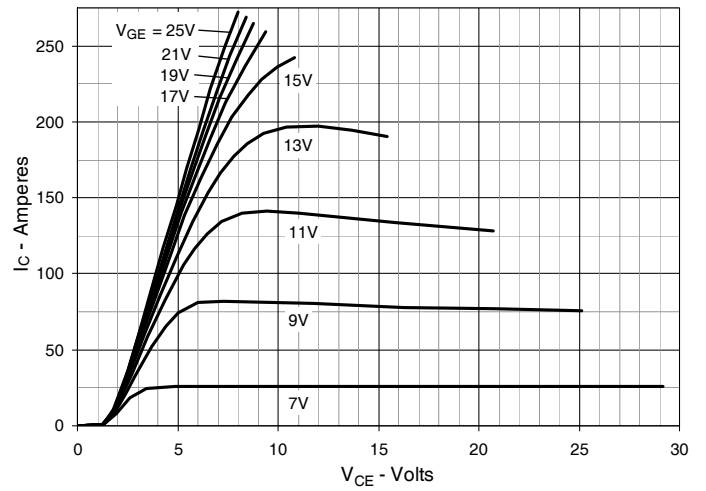
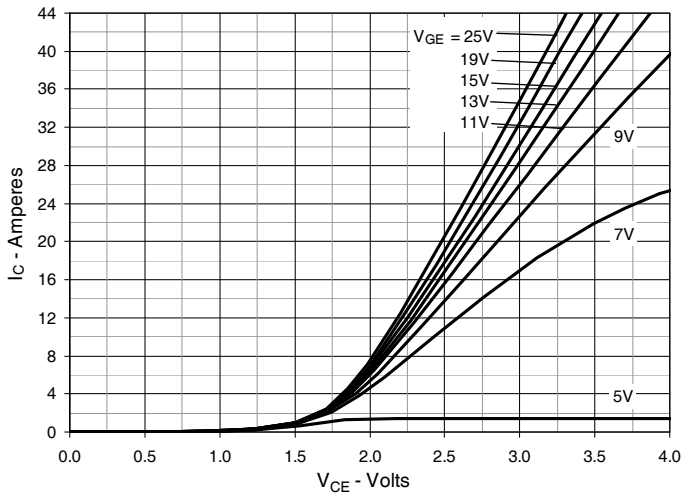
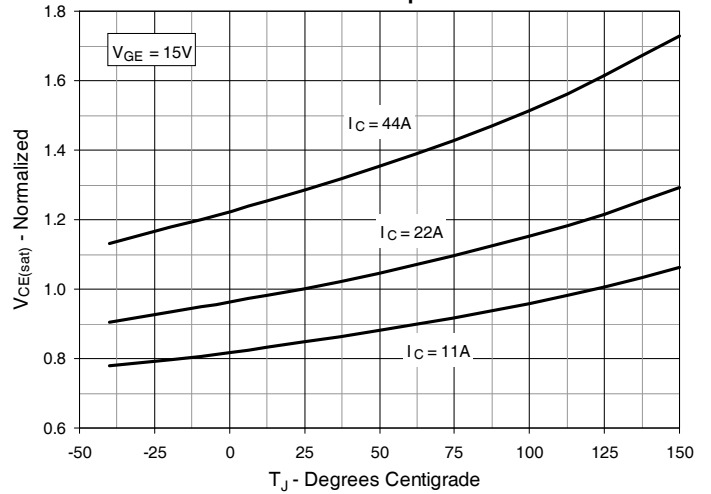
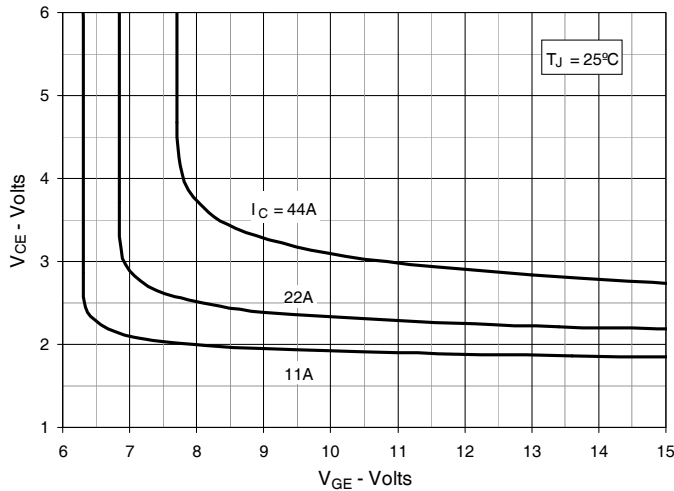
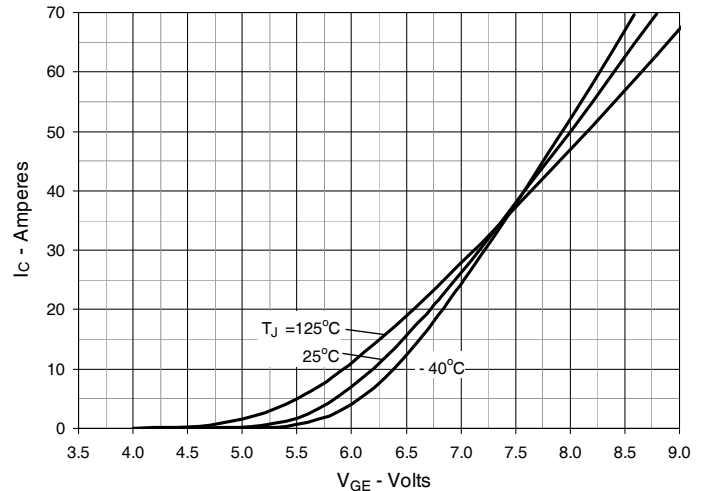
Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
$V_F$	$I_F = 22\text{A}, V_{GE} = 0\text{V}$ , Note 1			2.7 V
$t_{rr}$	$I_F = 11\text{A}, V_{GE} = 0\text{V}, -di_F/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}, V_{GE} = 0\text{V}$		1.4	$\mu\text{s}$
$I_{RM}$			30	A
$Q_{RM}$			21	$\mu\text{C}$

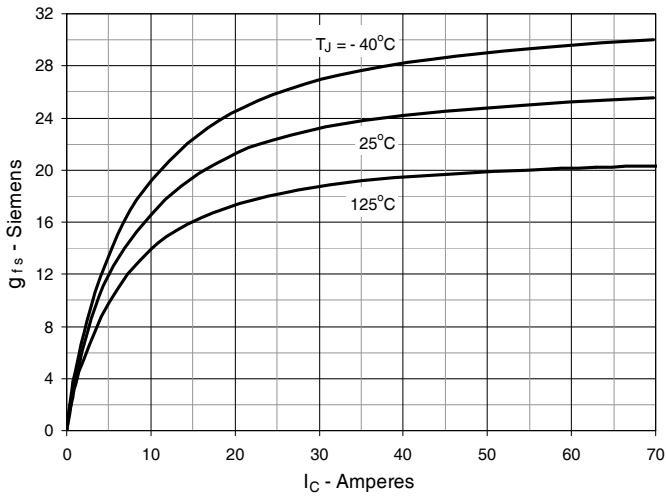
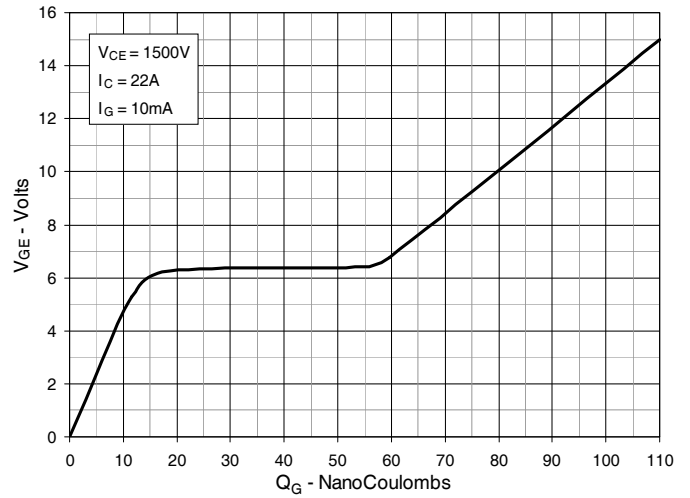
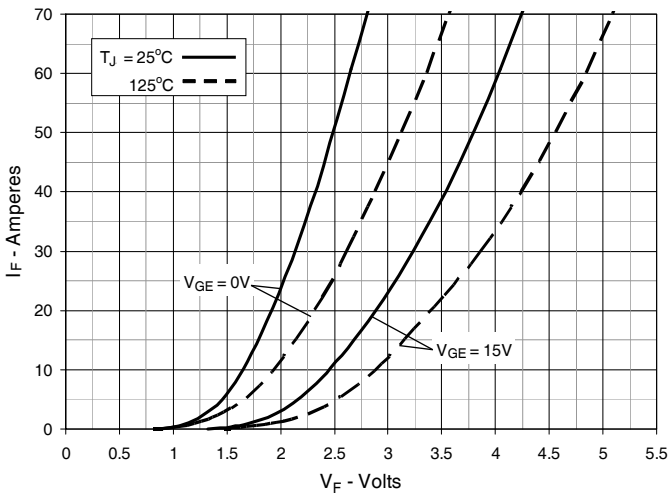
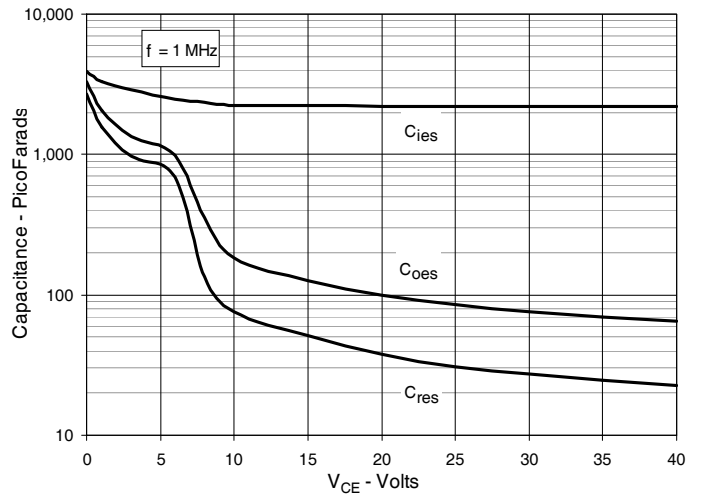
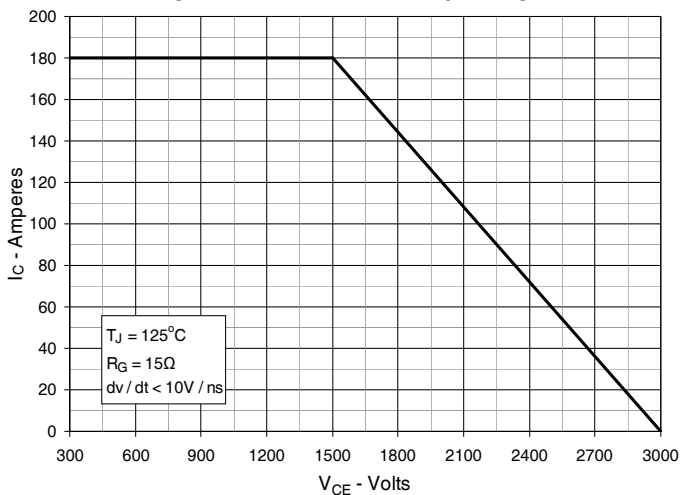
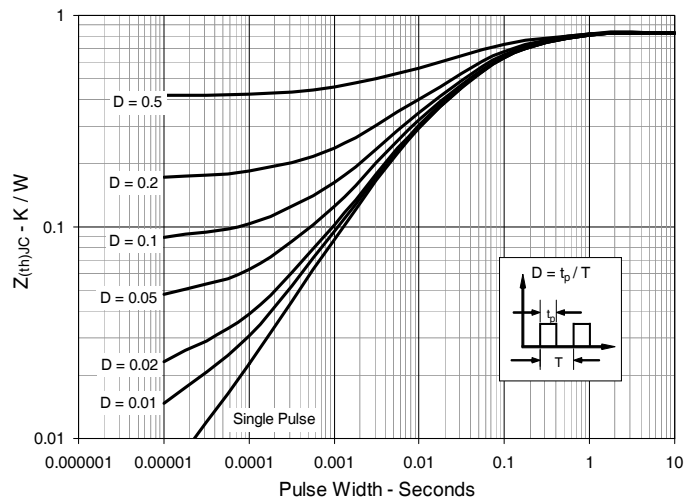
**Notes:**

1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .
2. Device must be heatsunk for high temperature leakage current measurements to avoid thermal runaway.

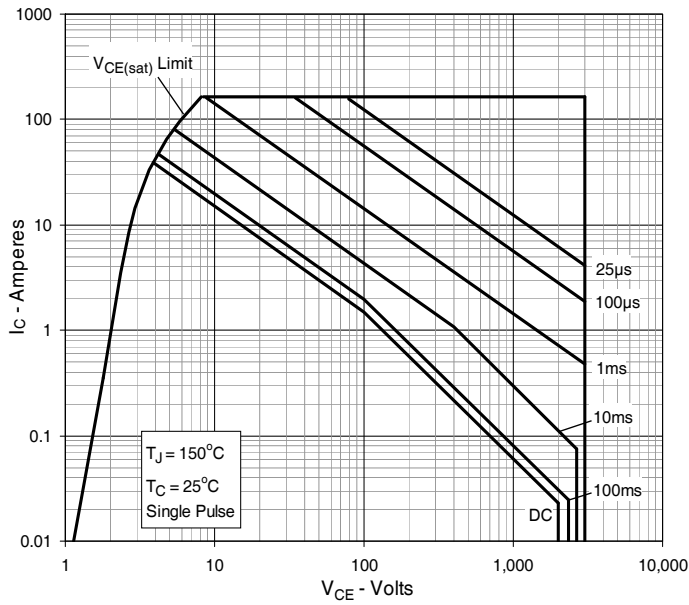
Additional provisions for lead-to-lead voltage isolation are required at  $V_{CE} > 1200\text{V}$ .

IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

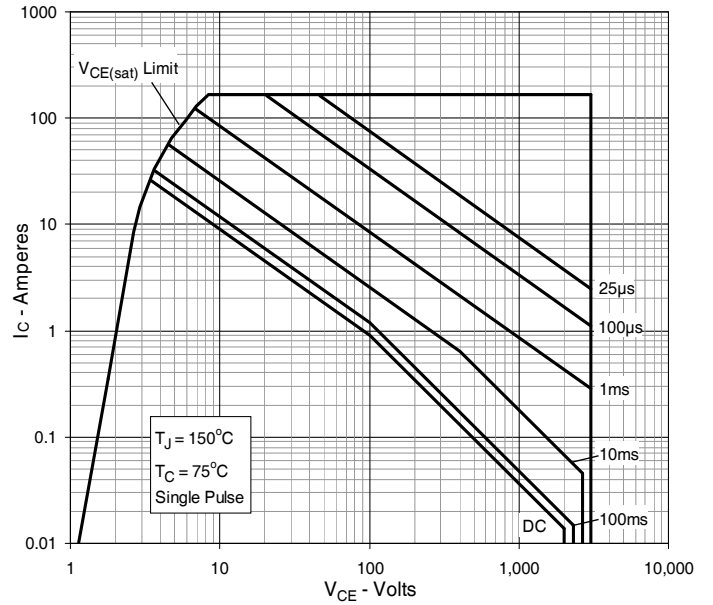
**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$** 

**Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$** 

**Fig. 3. Output Characteristics @  $T_J = 125^\circ\text{C}$** 

**Fig. 4. Dependence of  $V_{CE(sat)}$  on Junction Temperature**

**Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage**

**Fig. 6. Input Admittance**


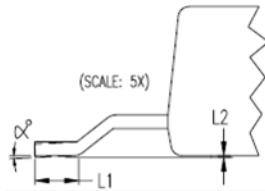
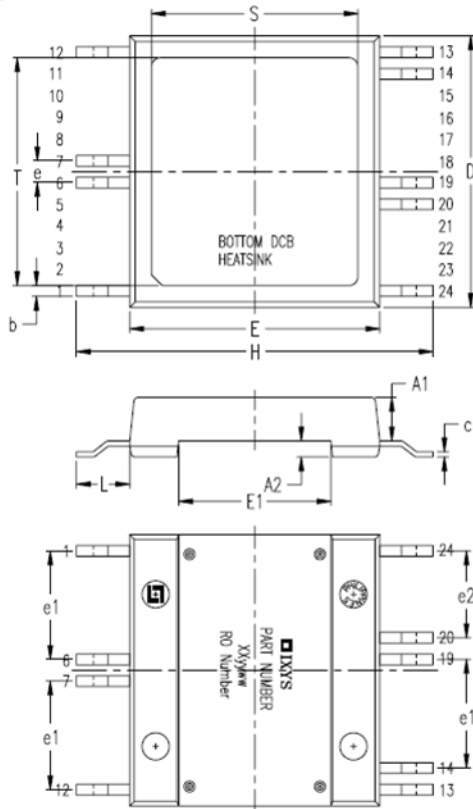
**Fig. 7. Transconductance**

**Fig. 8. Gate Charge**

**Fig. 9. Forward Voltage Drop of Intrinsic Diode**

**Fig. 10. Capacitance**

**Fig. 11. Reverse-Bias Safe Operating Area**

**Fig. 12. Maximum Transient Thermal Impedance**


**Fig. 13. Forward-Bias Safe Operating Area @  $T_C = 25^\circ\text{C}$**



**Fig. 14. Forward-Bias Safe Operating Area @  $T_C = 75^\circ\text{C}$**



**Package Outline**


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.209	.224	5.30	5.70
A1	.154	.161	3.90	4.10
A2	.055	.063	1.40	1.60
b	.035	.045	0.90	1.15
c	.018	.026	0.45	0.65
D	.976	.994	24.80	25.25
E	.898	.915	22.80	23.25
E1	.543	.559	13.80	14.20
e	.079 BSC		2.00 BSC	
e1	.394 BSC		10.00 BSC	
e2	.315 BSC		8.00 BSC	
H	1.272	1.311	32.30	33.30
L	.181	.209	4.60	5.30
L1	.051	.067	1.30	1.70
L2	.000	.006	0.00	0.15
S	.736	.760	18.70	19.30
T	.815	.839	20.70	21.30
α	0	4°	0	4°